

Title (en)

Method for casting copper and alloys containing copper

Title (de)

Verfahren zum Vergießen von Kupfer und kupferhaltigen Legierungen

Title (fr)

Procédé de coulée de cuivre et d'alliages contenant du cuivre

Publication

EP 2133165 B1 20131120 (DE)

Application

EP 09160173 A 20090513

Priority

DE 102008026535 A 20080603

Abstract (en)

[origin: EP2133165A1] Process for casting copper and copper alloys, comprises: providing a mold; applying a coating on the inner wall of the mold, where the coating comprises at least one inorganic oxide and a binder; solidifying the coating; filling a melt of copper or copper alloy into the mold, where the mold is heated to 60-200[deg] C before the filling process; and extracting the resulting cast from the mold. Independent claims are included for: (1) reusable molds hydrophobic coating, produced from a coating comprising at least one inorganic oxide, at least 1 wt.% of polysiloxane and a binder; and (2) a mold with extended stable time comprising a hydrophobic coating, where the mold is temperature controlled at 60-200[deg] C.

IPC 8 full level

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CPC (source: EP)

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Cited by

DE102010056146A1; US10391552B2; EP2871008A3; CN116496830A; WO2015051991A1; WO2014009359A3

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